

# MA3XD11

## Silicon epitaxial planar type

For high frequency rectification

### ■ Features

- Forward current (Average)  $I_{F(AV)} = 1$  A rectification is possible
- Low forward voltage  $V_F$

### ■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

Parameter	Symbol	Rating	Unit
Reverse voltage	$V_R$	20	V
Repetitive peak reverse voltage	$V_{RRM}$	25	V
Forward current (Average) *1	$I_{F(AV)}$	1.0	A
Non-repetitive peak forward surge current *2	$I_{FSM}$	3	A
Junction temperature	$T_j$	125	$^\circ\text{C}$
Storage temperature	$T_{stg}$	-55 to +125	$^\circ\text{C}$

Note) \*1: Mounted on an alumina PC board

\*2: The peak-to-peak value in one cycle of 50 Hz sine wave (non-repetitive)

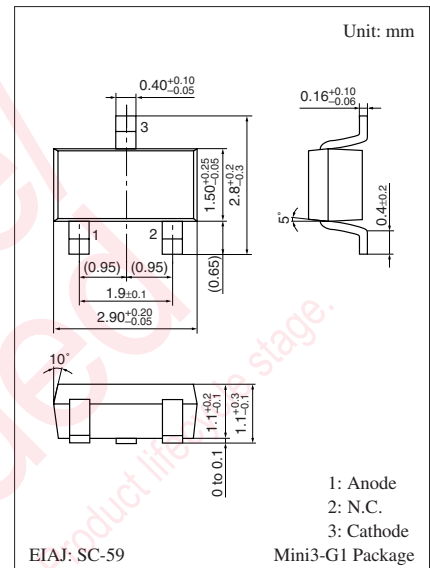
### ■ Electrical Characteristics $T_a = 25^\circ\text{C} \pm 3^\circ\text{C}$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	$V_F$	$I_F = 1.0$ A			0.45	V
Reverse current	$I_R$	$V_R = 20$ V			200	$\mu\text{A}$
Terminal capacitance	$C_t$	$V_R = 0$ V, $f = 1$ MHz		180		pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

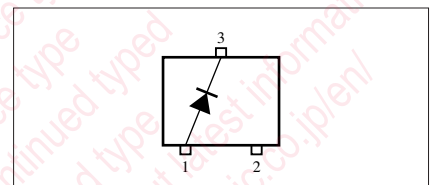
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

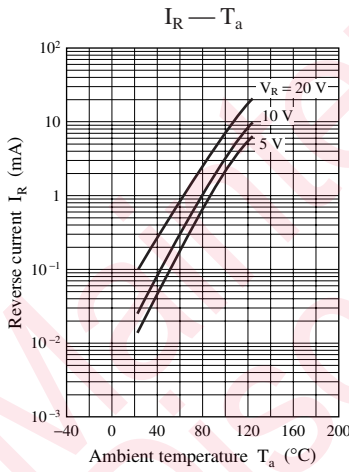
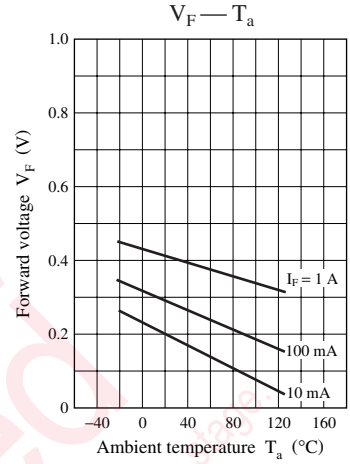
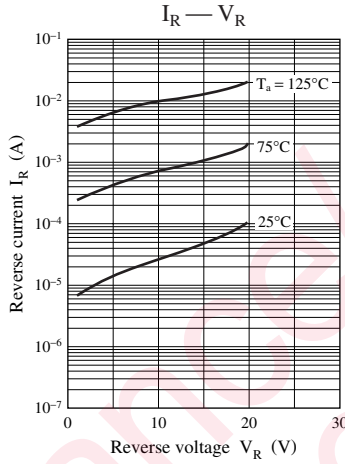
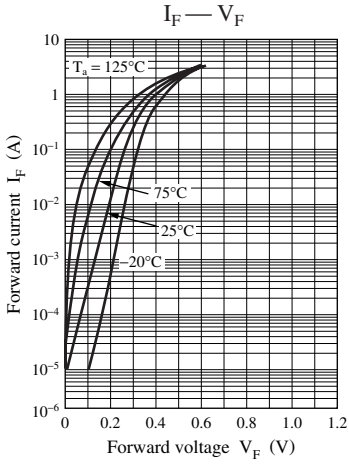
3. Absolute frequency of input and output is 400 MHz.



Marking Symbol: M6K

Internal Connection





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